

IN THE CLAIMS

26. (Currently Amended) A method for processing a circuit board, the method comprising:

providing a circuit board;

forming a set of pads on the circuit board; and

placing a solder mask layer over the formed set of pads, the solder mask defining a set of solder apertures for the set of pads, each solder aperture of the set of solder apertures having a set of rounded corners configured for a high bond strength solder joint;

wherein placing the solder mask layer includes:

creating a set of surface mount contacts, each surface mount contact having a main portion, and multiple convex lobes integrated with the main portion,

further comprising:

printing solder paste substantially consisting of flux and substantially lead-free solder over the set of pads; and

soldering a component to the set of pads using the printed solder paste.